



# N-Channel 20-V (D-S) 175 °C MOSFET

PRODUCT SUMMARY				
V <sub>(BR)DSS</sub> (V)	$r_{DS(on)}(\Omega)$ $I_{D}(A)^{2}$			
20	0.0045 at V <sub>GS</sub> = 10 V	60		
20	0.0065 at V <sub>GS</sub> = 4.5 V	60		

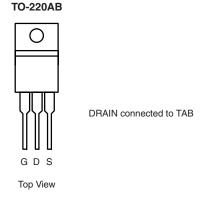
### **FEATURES**

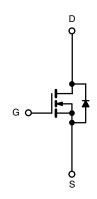
- TrenchFET® Power MOSFET
- 175 °C Junction Temperature
- 100 % R<sub>q</sub> Tested
- 100 % UIS Tested



### **APPLICATIONS**

OR-ing





N-Channel MOSFET

Ordering Information: SUP60N02-4m5P-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS	$\bullet$ $I_A = 25$ $^{\circ}$ C, unless our	erwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	$V_{DS}$	20	V		
Gate-Source Voltage	V <sub>GS</sub>	± 20	ľ		
Continuous Drain Current (T <sub>.I</sub> = 175 °C)	T <sub>C</sub> = 25 °C		60 <sup>a</sup>	А	
Continuous Diain Guitent (1j = 173 G)	T <sub>C</sub> = 100 °C	I <sub>D</sub>	60 <sup>a</sup>		
Pulsed Drain Current	I <sub>DM</sub>	120	Α .		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	50	1	
Single Pulse Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	125	mJ	
Mariana Barra Birata di ah	T <sub>C</sub> = 25 °C	В	120 <sup>c</sup>	w	
Maximum Power Dissipation <sup>b</sup>	T <sub>A</sub> = 25 °C <sup>d</sup>	P <sub>D</sub>	3.75		
Operating Junction and Storage Temperature Ra	ange	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) <sup>d</sup>	R <sub>thJA</sub>	40	°C/W		
Junction-to-Case	R <sub>thJC</sub>	1.25	C/ VV		

### Notes:

- a. Package limited.

- b. Duty cycle ≤ 1 %.
  c. See SOA curve for voltage derating.
  d. When mounted on 1" square PCB (FR-4 material).

## SUP60N02-4m5P

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	<u> </u>				<u>l</u>		
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{DS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			.,	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.0		3	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1	μΑ	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			50		
		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 175 ^{\circ}\text{C}$			250	1	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	100			Α	
		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$		0.0036	0.0045		
Durin Course On Olada Davidana a	_	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C			0.0068	0	
Drain-Source On-State Resistance <sup>a</sup>	r <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 175 ^{\circ}\text{C}$			0.008	Ω	
		$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0052	0.0065		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 20 \text{ A}$		95		S	
Dynamic <sup>b</sup>					'		
Input Capacitance	C <sub>iss</sub>			5950		pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 10 \text{ V}, f = 1 \text{ MHz}$		985			
Reverse Transfer Capacitance	C <sub>rss</sub>			365			
Total Gate Charge <sup>b</sup>	Qg			33	50	nC	
Gate-Source Charge <sup>b</sup>	$Q_{gs}$	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 50 \text{ A}$		18			
Gate-Drain Charge <sup>b</sup>	$Q_{gd}$			7			
Gate Resistance	R <sub>g</sub>		0.75	1.5	2.3	Ω	
Turn-On Delay Time <sup>b</sup>	t <sub>d(on)</sub>			15	25		
Rise Time <sup>b</sup>	t <sub>r</sub>	$V_{DD}$ = 10 V, $R_L$ = 0.2 $\Omega$		7	11	ns	
Turn-Off Delay Time <sup>b</sup>	t <sub>d(off)</sub>	$I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1.0 \Omega$		35	55		
Fall Time <sup>b</sup>	t <sub>f</sub>			8	12		
Source-Drain Diode Ratings and Cha	aracteristics 7	<sub>C</sub> = 25 °C <sup>c</sup>	l	•			
Continuous Current	I <sub>S</sub>				60	^	
Pulsed Current	I <sub>SM</sub>				100	A	
Forward Voltage <sup>a</sup>	$V_{SD}$	$I_F = 20 \text{ A}, V_{GS} = 0 \text{ V}$		0.85	1.5	٧	
Reverse Recovery Time	t <sub>rr</sub>			45	90	ns	
Peak Reverse Recovery Current	I <sub>RM</sub>	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}$		1.7	3.4	Α	
Reverse Recovery Charge	Q <sub>rr</sub>			0.039	0.155	μС	

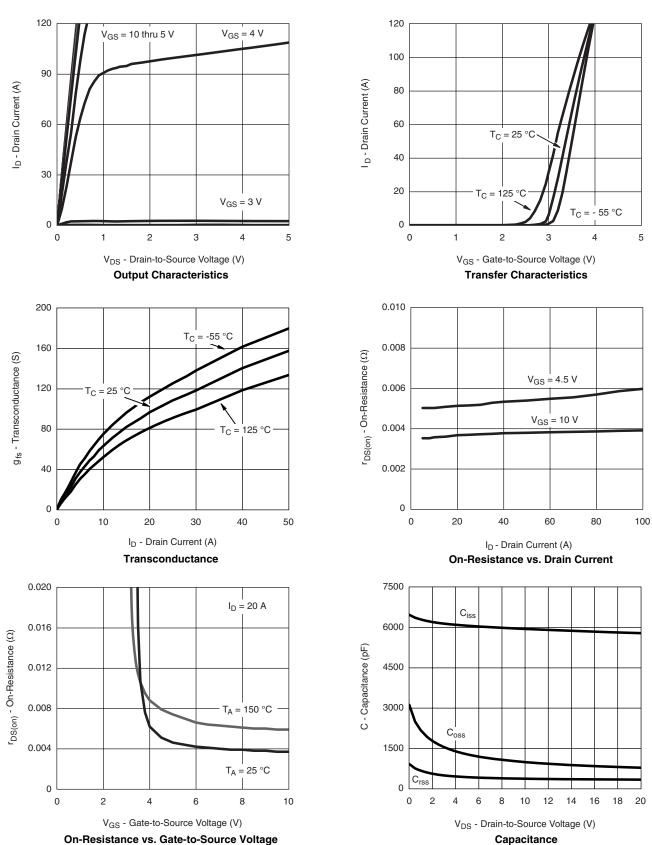
### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%$
- b. Independent of operating temperature.
- c. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

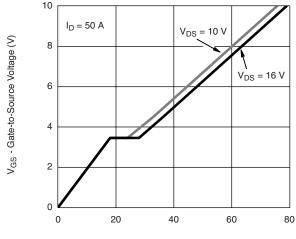


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

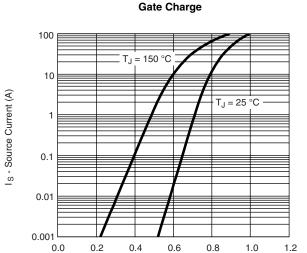


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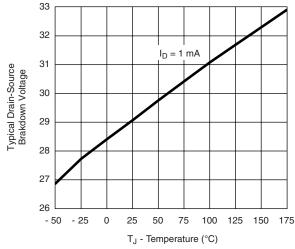
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



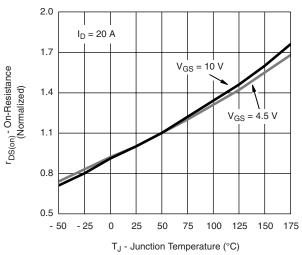
Q<sub>g</sub> - Total Gate Charge (nC)



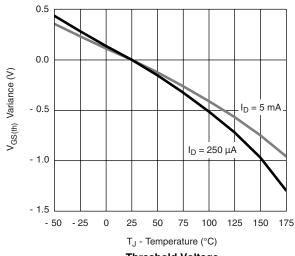
V<sub>SD</sub> - Source-to-Drain Voltage (V) Source-Drain Diode Forward Voltage



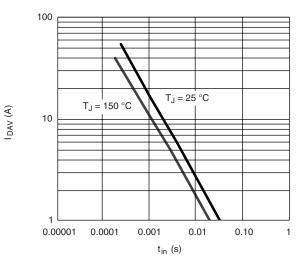
Typical Drain-source Brakdown Voltage vs. Junction Temperature



On-Resistance vs. Junction Temperature



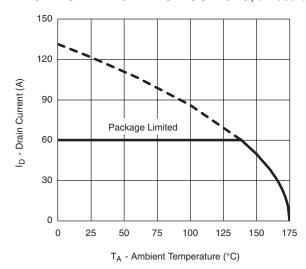
**Threshold Voltage** 

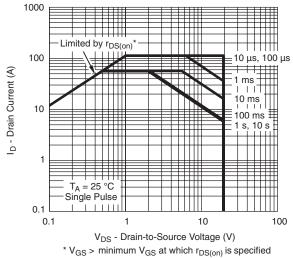


Single Pulse Avalanche Current vs. Time



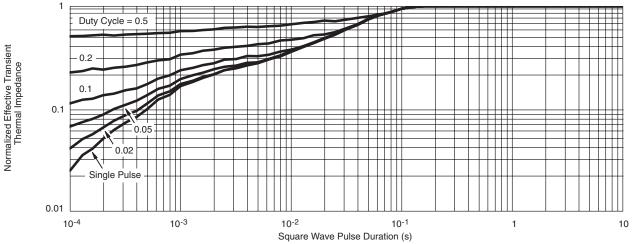
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





**Drain Current vs. Ambient Temperature** 





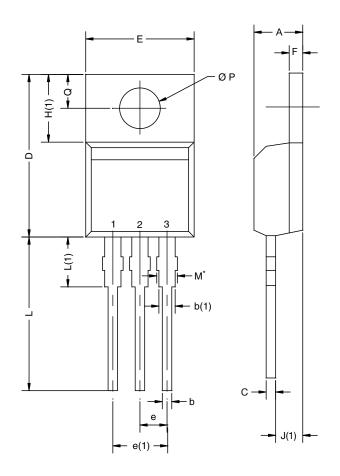
Normalized Thermal Transient Impedance, Junction-to-Case

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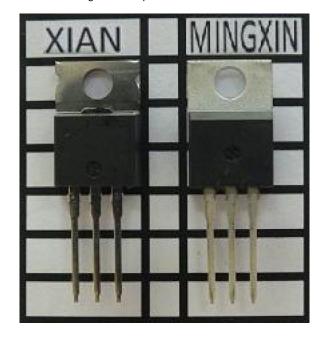
## **TO-220AB**



	MILLIN	IETERS	INC	HES		
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	4.25	4.65	0.167	0.183		
b	0.69	1.01	0.027	0.040		
b(1)	1.20	1.73	0.047	0.068		
С	0.36	0.61	0.014	0.024		
D	14.85	15.49	0.585	0.610		
Е	10.04	10.51	0.395	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.09	6.48	0.240	0.255		
J(1)	2.41	2.92	0.095	0.115		
L	13.35	14.02	0.526	0.552		
L(1)	3.32	3.82	0.131	0.150		
ØР	3.54	3.94	0.139	0.155		
Q	2.60	3.00	0.102	0.118		
ECN: X12-0208-Rev. N, 08-Oct-12 DWG: 5471						

## Notes

- $^{\star}$  M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM
- · Xi'an and Mingxin actual photo





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Revision: 02-Oct-12 Document Number: 91000

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